



8/10/02
7/10/02
500.39825X00
W. J. KURT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): T. HIROSE, et al

Serial No.: 09/800,495

Filed: March 8, 2001

For: METHOD OF DETECTING AND MEASURING ENDPOINT OF
POLISHING PROCESSING AND ITS APPARATUS AND
METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE
USING THE SAME

Group: 3723

Examiner: D. Nguyen

AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

July 8, 2002

RECEIVED
JUL - 9 2002
TC 3700 MAIL ROOM

Sir:

The following amendments and remarks are respectfully submitted in connection with the above-identified application in response to the Office Action dated June 6, 2002.

IN THE CLAIMS:

Please amend claim 1 as follows:

~~Sub 1~~ 1. (amended) A method of detecting an endpoint of polishing processing, comprising the steps of:
concurrently irradiating a film formed on a surface of a wafer under polishing processing with light having two or more different wavelengths;
detecting reflected lights from said film caused by the irradiation; and
detecting the endpoint of polishing processing of said film on the basis of a relationship between intensities of the detected reflected lights.